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(21) International Application Number: PCT/US99/06453 (22) International Filing Date: 26 March 1999 (26.03.99) (30) Priority Data: 60/079,746 27 March 1998 (27.03.98) US (71) Applicant (for all designated States except US): TRUSTEES OF PRINCETON UNIVERSITY [US/US]; P.O. Box 36, Princeton, NJ 08544-0036 (US). (72) Inventor; and (75) Inventor/Applicant (for US only): WAGNER, Sigurd [US/US]; 16 Malcom Circle, Princeton, NJ 08540 (US). (74) Agent: FRISCIA, Michael, R.; Friscia & Nussbaum, One University Plaza, Hackensack, NJ 07601 (US).		(81) Designated States: AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CU, CZ, DE, DK, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, UA, UG, US, UZ, VN, YU, ZW, ARIPO patent (GH, GM, KE, LS, MW, SD, SL, SZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GW, ML, MR, NE, SN, TD, TG). Published <i>With international search report. Before the expiration of the time limit for amending the claims and to be republished in the event of the receipt of amendments.</i>
(54) Title: METHOD FOR MAKING MULTILAYER THIN-FILM ELECTRONICS		
(57) Abstract <p>Multilayer thin-film electronics are manufactured at high speed, even while the various component functions are manufactured separately under conditions tailored to optimize component performance and yield. Each function or group of functions is fabricated on a separate flexible substrate. These flexible substrates are bonded to each other using adhesive films that are anisotropic electrical conductors or optical light guides. The bonding is performed by laminating the flexible substrates to each other in a continuous process, using the anisotropic conductor as the bonding layer.</p>		